

07-24-2002

Docket No.: 57775 (71987)

HEET

U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Of



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102166613

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of conveying party(ies):

Chien-Ping HUANG

07/10/02

2. Name and address of receiving party(ies):

Name: Siliconware Precision Industries Co., Ltd.

Address: No. 123, Sec. 3, Da Fong Road, Tantz, Taichung, Taiwan, R.O.C.

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

City: _____ State/Prov.: _____

Country: _____ ZIP: _____

Execution Date: July 3, 2002

Additional name(s) & address(es)

☐ Yes ☒ No

4. Application number(s) or patent numbers(s):

10/192399

If this document is being filed together with a new application, the execution date of the application is: July 10, 2002

Patent Application No.

Filing date

B. Patent No.(s)

07/16/2002 HMDOR1 00000071 10192399

03 FC:581

40.00 DP

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Peter F. Corless

Registration No. 33,860

Address: EDWARDS & ANGELL, LLP

P.O. Box 9169

City: Boston State/Prov.: MA

Country: USA ZIP: 02209

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Peter F. Corless

Name of Person Signing

Signature

July 10, 2002

Date

2

Total number of pages including cover sheet, attachments, and

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PATENT
REEL: 013102 FRAME: 0420

21645 (36-396)

ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

Inventor(s) Chien-Ping HUANG

Full Name(s) _____

Hereby sell, assign and transfer to

Assignee SILICONWARE PRECISION INDUSTRIES, LTD.
 Name and Address No. 123, Sec. 3, Da Fong Road, Tantz, Taichung,
Taiwan, R.O.C.

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled

Title of Invention: FLIP-CHIP BALL GRID ARRAY SEMICONDUCTOR
PACKAGE WITH HEAT-DISSIPATING DEVICE AND METHOD FOR
FABRICATING THE SAME

Which application was

Complete either a) executed by the undersigned on _____
 b) filed on the _____
 Serial No. _____

Including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date _____ Signed at TAICHUNG, TAIWAN, R.O.C.
 On _____

Inventor(s) → Chien-Ping Huang Chien-Ping HUANG
 Full Signature(s) _____